

## EMBEDDED PASSIVES

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*The aim of this presentation is to show the current situation in the area of embedded (buried) passives made in Low Temperature Cofired Ceramic (LTCC) and Printed Circuit Board (PCB) technologies. The material, technological and constructional solutions as well as their relation with chosen electrical and stability properties are analyzed in details for modern embedded micropassives, both described in the literature or fabricated and/or characterized at the Faculty of Microsystem Electronics and Photonics, Wrocław University of Science and Technology. The role of such components in modern electronic circuits is also discussed.*